Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-4. (Canceled)

5. (Currently amended) A method for producing a solar cell module comprising:

a step for providing a plurality of solar cell elements each having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

a step for connecting a first connection tab ~~to~~ and the front surface electrode of one of the solar cell elements, ~~through~~ by melting a first solder layer that is disposed therebetween;

a step for connecting a second connection tab ~~to~~ and the back surface electrode of another of the solar cell elements, ~~through~~ by melting a second solder layer ~~having~~ that is disposed therebetween and has a different melting point than the first solder layer; and

a step for connecting the first connection tab ~~to~~ and the second connection tab.

6. (Previously presented) The method for producing a solar cell module according to claim 5, wherein the first solder layer has a higher melting point than the second solder layer.

7. (Previously presented) The method for producing a solar cell module according to claim 6, wherein the first solder layer is substantially free of lead.

8. (Previously presented) The method for producing a solar cell module according to claim 5, wherein the first or the second connection tab is provided with a through hole at a connection area between the connection tab and the front surface electrode or the back surface electrode.

9. (Previously presented) The method for producing a solar cell module according to claim 5, wherein the connection tabs are connected to a common connection line by means of a solder, and the connection tabs are provided with through holes at connection areas between the connection tabs and the common connection line.

10. (Previously presented) The method for producing a solar cell module according to claim 5, wherein the connection tabs are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the connection tabs.

11. (Previously presented) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

12. (Previously presented) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

13-22. (Canceled)

23. (Previously presented) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the electrode with the solder layer before the step for connecting a first connection tab to the front surface electrode of one of the solar cell elements, through a first solder layer; the step for connecting a second connection tab to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and the step for connecting the first connection tab to the second connection tab.

24. (Previously presented) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the connection tab with the solder layer before the step for connecting a first connection tab to the front surface electrode of one of the solar cell elements, through a first solder layer; the step for connecting a second connection tab to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and the step for connecting the first connection tab to the second connection tab.

25. (Currently amended) A method for producing a solar cell module, comprising:

a step for providing a solar cell element having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

a step for connecting a first connection tab ~~to~~ and the front surface electrode or the back surface electrode of the solar cell element, ~~through~~ by melting a first solder layer that is disposed therebetween; and

a step for connecting a second connection tab ~~to~~ and an electrode of the solar cell element to which the first connection tab is not connected, ~~through~~ by melting the second solder layer ~~having~~ tha t is disposed therebetween and has a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.

26. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the first solder layer is substantially free of lead.

27. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the first or the second connection tab is provided with a through hole at a connection area between the connection tab and the front surface electrode or the back surface electrode.

28. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the connection tabs are connected to a common connection line by means of a solder, and the connection tabs are provided with through holes at connection areas between the connection tabs and the common connection line.

29. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the connection tabs are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the connection tabs.

30. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

31. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

32. (Previously presented) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the electrode with the solder layer before the step for connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and the step for connecting a second connection tab to an electrode of the solar cell element to which the first connection tab is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.

33. (Previously presented) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the connection tab with the solder layer before the step for connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and the step for connecting a second connection tab to an electrode of the solar cell element to which the first connection tab is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above step for connecting the first connection tab.